

DF15005 THRU DF1510

List

List.....	1
Package outline.....	2
Features.....	2
Mechanical data.....	2
Maximum ratings	2
Rating and characteristic curves.....	3
Pinning information.....	4
Marking.....	4
Tube packing.....	4
Suggested thermal profiles for soldering processes.....	5
High reliability test capabilities.....	6

DF15005 THRU DF1510

1.5A Miniature Glass Passivated Single-Phase Bridge Rectifiers-50-1000V

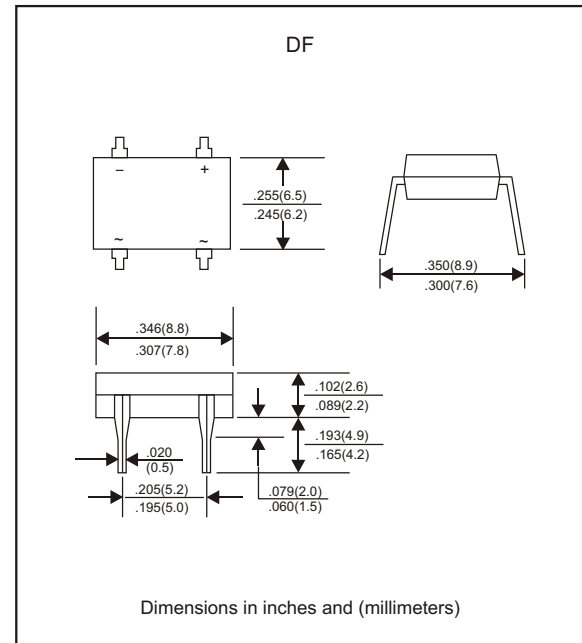
Features

- Surge overload ratings to 50 amperes peak.
- Recommended for non-automatic applications.
- Ideal for & save space on printed circuit board.
- Applicable for automatic insertion.
- Reliable low cost construction utilizing molded plastic technology results in inexpensive product.
- Glass passivated chip junctions.
- Lead-free parts meet RoHS requirements.
- UL recognized file # E321971

Mechanical data

- Epoxy: UL94-V0 rated flame retardant
- Case : Molded plastic, DF
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : marked on body
- Mounting Position : Any
- Weight : Approximated 1.00 gram

Package outline



Maximum ratings (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.1	I_O			1.5	A
Forward surge current	8.3ms single half sine-wave superimposed on rate load (JEDEC methode)	I_{FSM}			50	A
Reverse current	$V_R = V_{RRM} \quad T_A = 25^{\circ}\text{C}$	I_R			10	uA
	$V_R = V_{RRM} \quad T_A = 100^{\circ}\text{C}$				500	
Storage temperature		T_{STG}	-65		+175	$^{\circ}\text{C}$

SYMBOLS	V_{RRM}^{*1} (V)	V_{RMS}^{*2} (V)	V_R^{*3} (V)	V_F^{*4} (V)	Operating temperature $T_J, (^{\circ}\text{C})$
DF15005	50	35	50	1.10	-55 to +150
DF1501	100	70	100		
DF1502	200	140	200		
DF1504	400	280	400		
DF1506	600	420	600		
DF1508	800	560	800		
DF1510	1000	700	1000		

*1 Repetitive peak reverse voltage

*2 RMS voltage

*3 Continuous reverse voltage

*4 Maximum forward voltage

Rating and characteristic curves (DF15005 THRU DF1510)

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

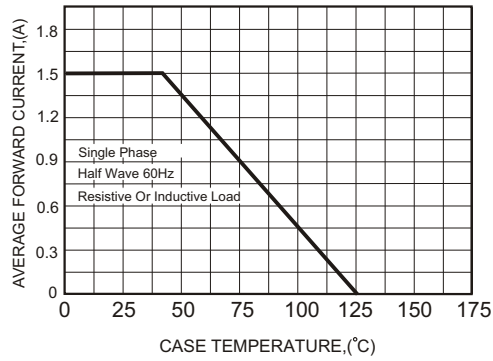


FIG.2-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

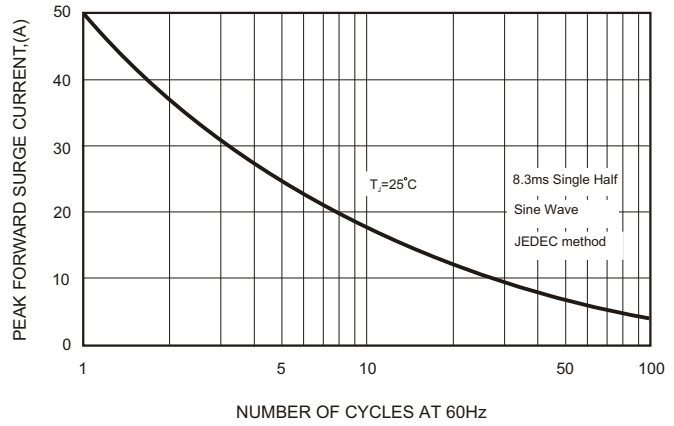


FIG.3-TYPICAL FORWARD CHARACTERISTICS

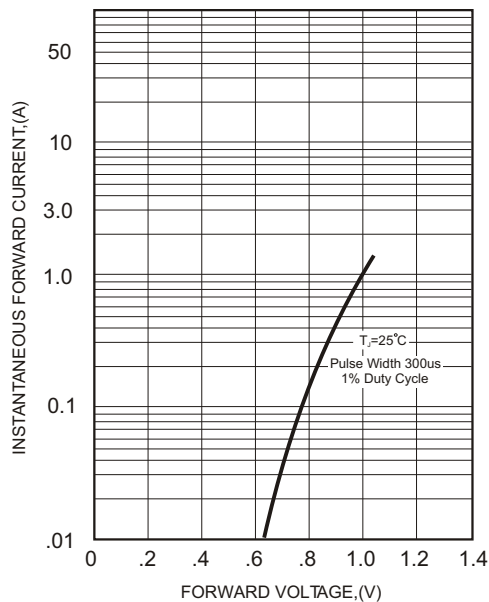
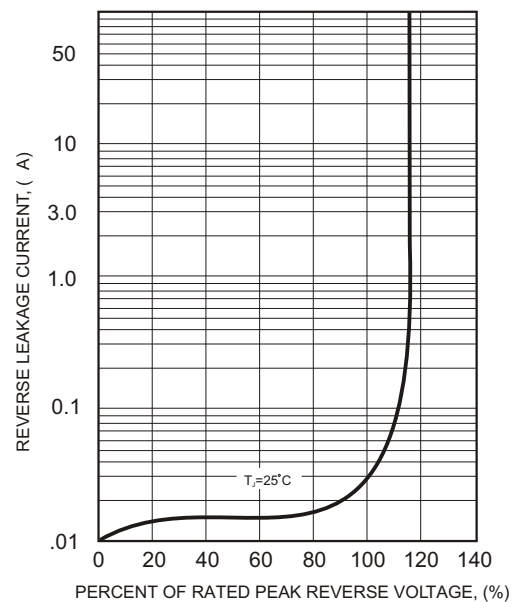
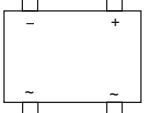
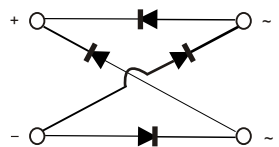


FIG.4-TYPICAL REVERSE CHARACTERISTICS



DF15005 THRU DF1510

Pinning information

Simplified outline	Symbol
	

Marking

Type number	Marking code
DF15005	DF15005
DF1501	DF1501
DF1502	DF1502
DF1504	DF1504
DF1506	DF1506
DF1508	DF1508
DF1510	DF1510

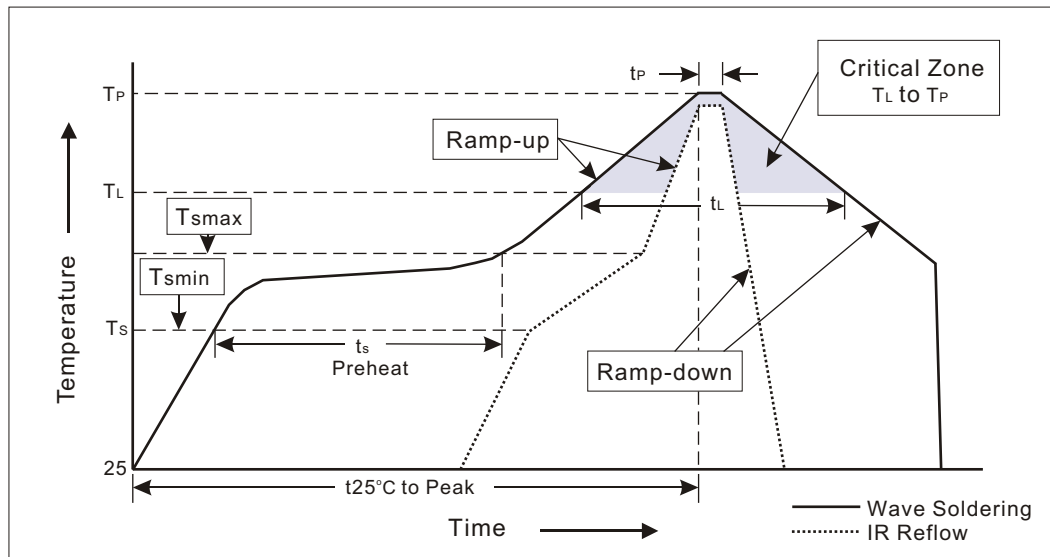
Tube packing

PACKAGE	TUBE (pcs)	TUBE SIZE (m/m)	BOX (pcs)	INNER BOX (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
DF	50	420*12.0*9.4	2500	470*145*73	490*240*310	15,000	11.0

DF15005 THRU DF1510

Suggested thermal profiles for soldering processes

1. Storage environment: Temperature=10°C~35°C Humidity=65%±15%
2. Reflow soldering of surface-mount devices



3. Flow (wave)soldering (solder dipping)

Profile Feature	Soldering Condition
Average ramp-up rate(T _L to T _P)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(ts)	100°C 150°C 60~120sec
Tsmax to T _L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T _L) -Time(t _L)	183°C 60~150sec
Peak Temperature(T _P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t _P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

DF15005 THRU DF1510

High reliability test capabilities

Item Test	Conditions	Reference
1. Solder Resistance	at $260 \pm 5^{\circ}\text{C}$ for $10 \pm 2\text{sec.}$ immerse body into solder $1/16" \pm 1/32"$	MIL-STD-750D METHOD-2031
2. Solderability	at $245 \pm 5^{\circ}\text{C}$ for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	$V_R = 80\%$ rate at $T_A = 150^{\circ}\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1026
4. Forward Operation Life	Rated average rectifier current at $T = 25^{\circ}\text{C}$ for 500hrs.	MIL-STD-750D METHOD-1027
5. Intermittent Operation Life	$T_A = 25^{\circ}\text{C}$, $I_F = I_O$ On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
6. Pressure Cooker	$15P_{SIG}$ at $T_A = 121^{\circ}\text{C}$ for 4 hrs.	
7. Temperature Cycling	-55°C to $+125^{\circ}\text{C}$ dwelled for 30 min. and transferred for 5 min. total 10 cycles.	MIL-STD-750D METHOD-1051
8. Thermal Shock	0°C for 5 min. rise to 100°C for 5 min. total 10 cycles.	MIL-STD-750D METHOD-1056
9. Forward Surge	8.3ms single half sine-wave superimposed on rated load, one surge.	MIL-STD-750D METHOD-4066-2
10. Humidity	at $T_A = 65^{\circ}\text{C}$, RH=98% for 1000hrs.	MIL-STD-750D METHOD-1038
11. High Temperature Storage Life	at 175°C for 1000hrs.	MIL-STD-750D METHOD-1031
12. Solvent Resistance	Dip into Freon at 25°C for 1 min.	MIL-STD-202F METHOD-215